



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

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re the Application of: **Shoji HARA, et al.**

Group Art Unit: 1762

Serial No.: 09/782,169

Examiner: **TALBOT Brian K.**

Filed: **February 14, 2001**

Confirmation No.: 2107

For: **LAMINATE COMPRISING POLYIMIDE AND CONDUCTOR LAYER, MULTI-LAYER WIRING BOARD WITH THE USE OF THE SAME AND PROCESS FOR PRODUCING THE SAME**

REQUEST FOR RECONSIDERATION AFTER FINAL REJECTION

Mail Stop AF

Commissioner for Patents

P.O. Box 1450

Alexandria, VA 22313-1450

Date: January 9, 2004

Sir:

In response to the Office Action dated **September 9, 2003**, applicants request favorable reconsideration of the above-identified application. Claims 1-13, 17 and 18 are pending.

Examiner Talbot is thanked for the courtesies extended to the undersigned attorney during the personal interview conducted on January 8, 2004. Applicant's separate record of the substance of that interview is incorporated into the following discussion.

Claims 1-13, 17 and 18 were rejected under 35 USC §103(a) as being unpatentable over Chen et al. or Shiotani et al. in combination with Ameen et al. Favorable reconsideration of this rejection is earnestly solicited.

The Examiner acknowledges that the primary references to Chen et al. and Shiotani et al. fail to teach a dry plating method and subsequent wet plating method to build up the conductor. However, the primary references also fail to teach directly forming the at least one conductor layer

BKT
do enter
2/29/04